



SOT505-2

plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm

8 June 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	TSSOP8
Package type industry code	TSSOP8
Package style descriptive code	TSSOP (thin shrink small outline package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-1-2002

Table 1. Package summary

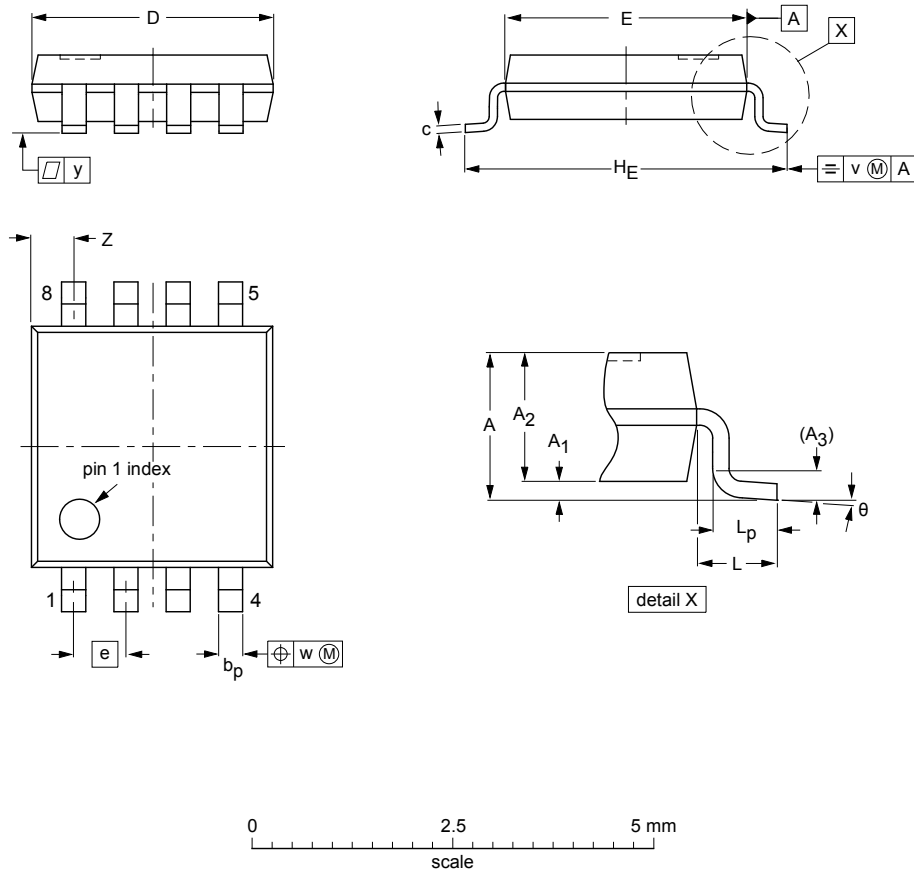
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.9	-	3	3.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	-	-	1.1	1.1	mm
A ₂	package height	0.75	-	0.85	0.95	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	8	-	



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2. Package outline

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm SOT505-2



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	v	w	y	Z ⁽¹⁾	θ
mm	1.1	0.15 0.00	0.95 0.75	0.25	0.38 0.22	0.18 0.08	3.1 2.9	3.1 2.9	0.65	4.1 3.9	0.5	0.47 0.33	0.2	0.13	0.1	0.70 0.35	8° 0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT505-2		---				02-01-16

Fig. 1. Package outline TSSOP8 (SOT505-2)

3. Soldering

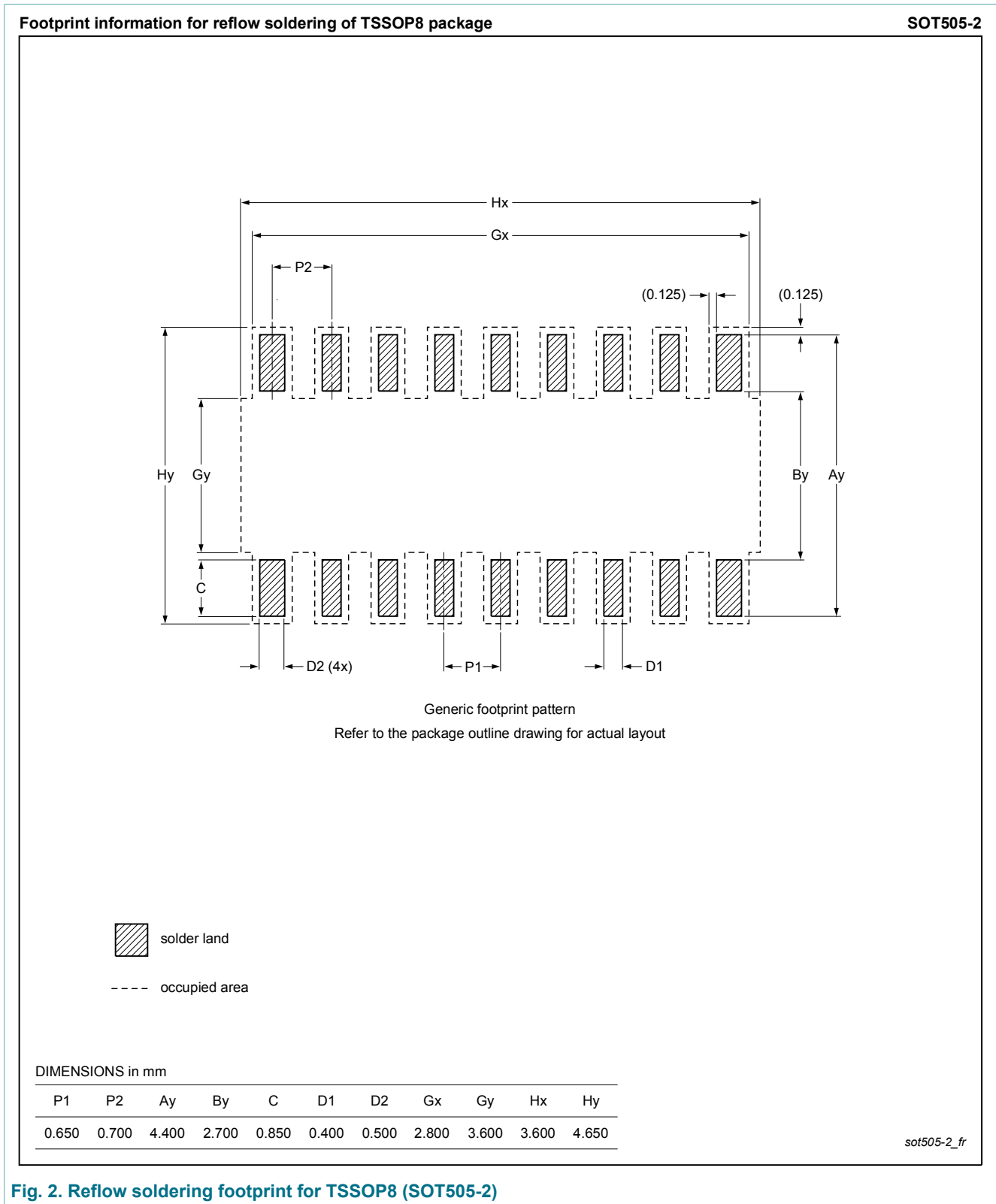


Fig. 2. Reflow soldering footprint for TSSOP8 (SOT505-2)

4. Legal information

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